
M24M01-DF package mechanical data modifications

Silicon identification

This errata sheet applies to the M24M01-DF, which is 1 Mbit serial I²C bus EEPROMs, and specifically to the device delivered in 8-bump wafer-level chip-scale packages (WLCSP).

The impacted part number is M24M01-DFCS6TP/K.

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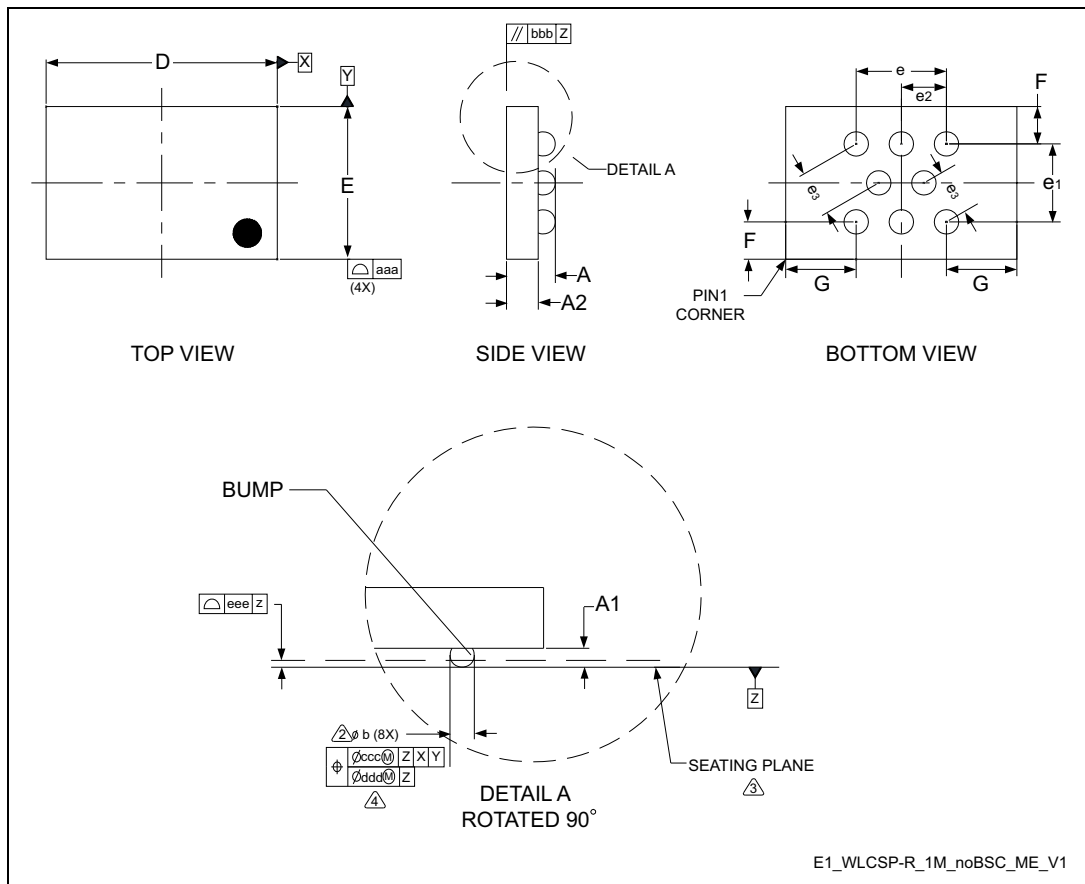
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1 M24M01-DF physical product change

There is not any physical product change.

Figure 1 shows the package outline.

Figure 1. WLCSP 8-bump, without BSC, 2.578 x 1.716 mm, wafer level chip scale package outline



The figures below show the difference between D and E dimensions in the front side view (see *Figure 2*), back side view (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

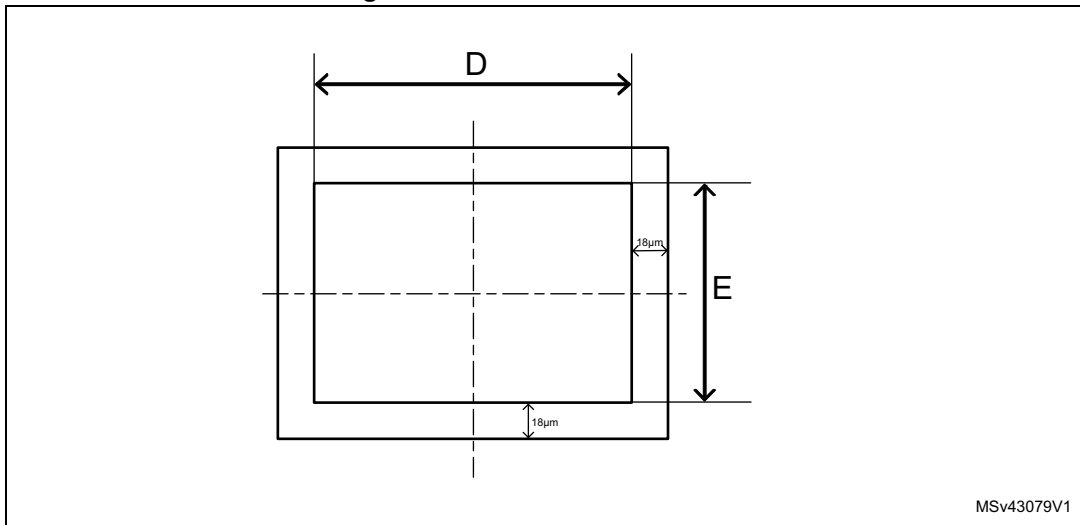


Figure 3. D and E back side view

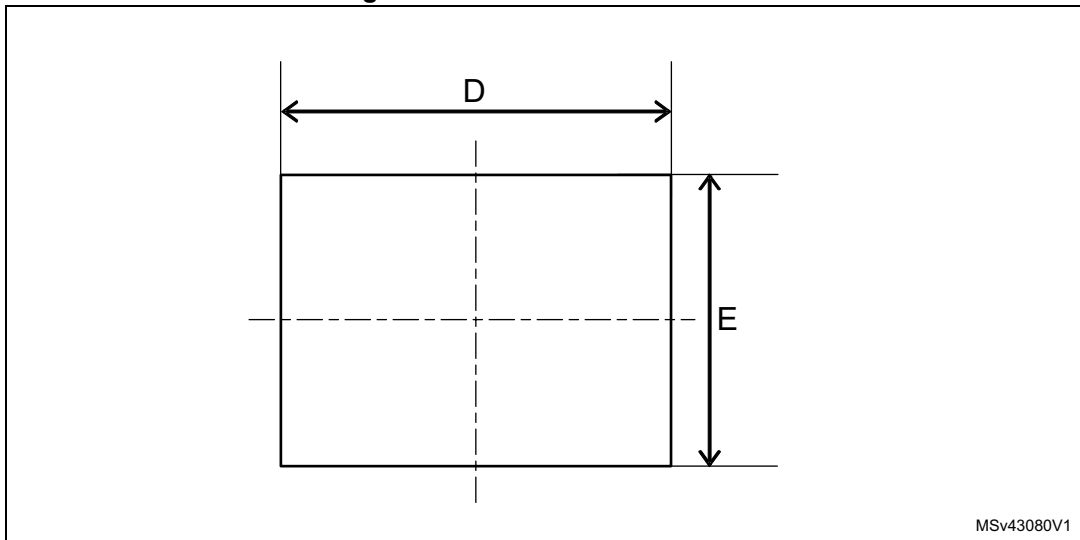
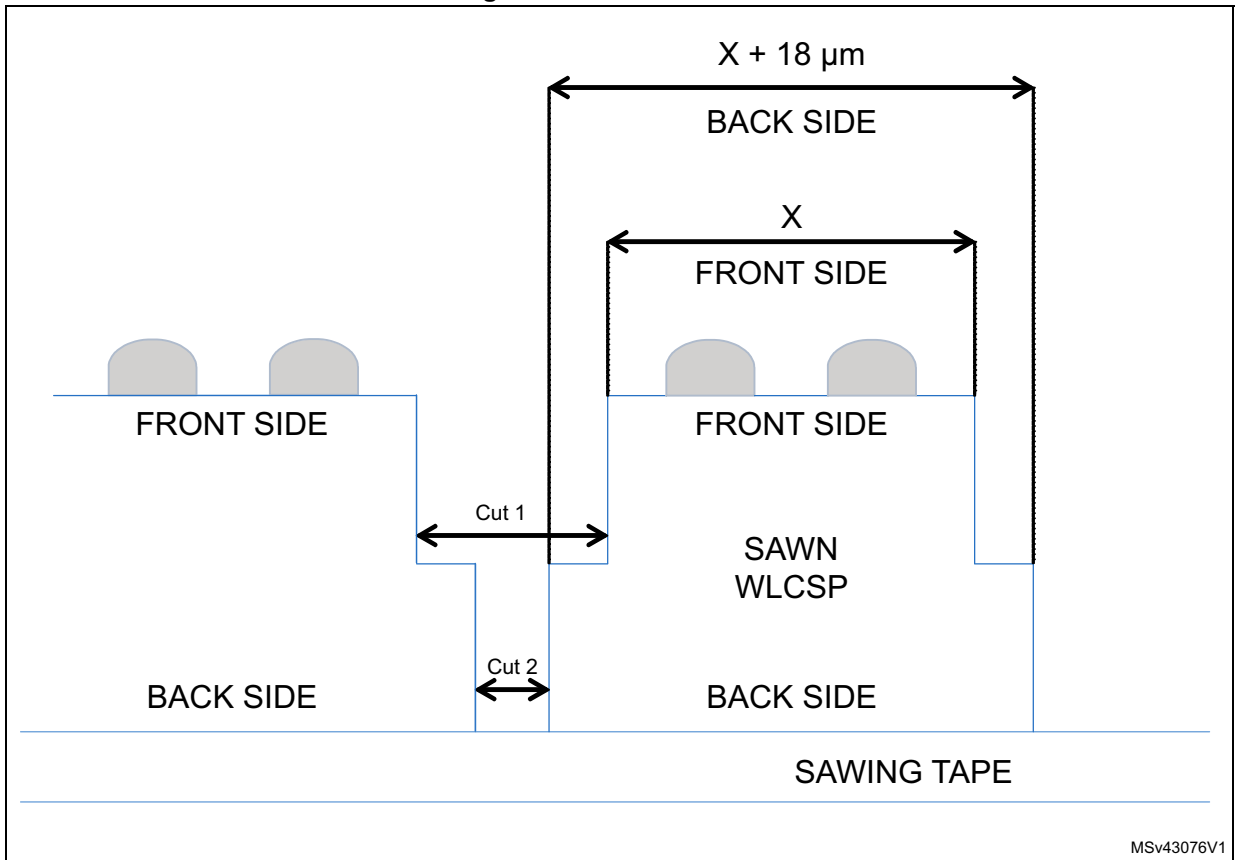


Figure 4. D or E side view



2 Package mechanical data modifications

This document refers to the changes in dimensions D and E (see [Figure 3](#)) described in the M24M01-DF datasheet, in tables detailing the dimensions of the WLCSP 8-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values in the M24M01-DF datasheet correspond to front side view (ball side), instead of back side view (marking side view).
[Table 1](#) and [Table 2](#) report the data for the front and back view, respectively.

Table 1. D and E values corresponding to front side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	2.560	2.580	-	0.1008	0.1016
E	-	1.698	1.718	-	0.0669	0.0676

Table 2. D and E values corresponding to back side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	2.578	2.598	-	0.1015	0.1023
E	-	1.716	1.736	-	0.0676	0.0683

The difference between back side and front side dimension is 18 µm (0.018 mm). This difference is due to the two-step sawing process, where cut 1 and cut 2 are performed with blades having different thicknesses (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).

3 Revision history

Table 3. Document revision history

Date	Revision	Changes
07-Jul-2016	1	Initial release.
13-Sep-2016	2	Deleted M24M01-R.

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